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Board Title:	GS66508T Half Bridge Evaluation Board
Part Number:	GSEVBHB08T
Revision:	B
Size (length x width):	120mm x 80mm
Shape:	Rectangular
Material:	0.063" +/- [10%] high Tg FR4
Number of Layers:	2
Component Type	Mixed, Both sides
Hole diameter	Finished hole size
Gold Finger	No
Impedance	No
Plug Vias:	None
Minimum Trace Width/Gap	0.3mm
Minimum Hole Size	0.3mm
Copper Thickness	2oz. Cu all layers
Board Surface Finish	ENIG Immersion Gold RoHS
Soldermask:	SMOBC. Green on both sides
Silkscreen:	Top and Bottom Sides, White
Paneling:	Not required. Allowable at discretion of board manufacturer if cost effective
Electrical Test:	Required
Special Info/Instructions:	<ol style="list-style-type: none"> 1. PCB Manufacturing process must be lead-free and RoHS compliant. 2. PCB Manufacturing must be compliant with IPC-A-6012 Class 2 3. Mechanical dimensions, drilling drawings and other manufacturing specifications provided in the *_FAB.PDF document. 4. Production release. No factory logo allowed. 5. UL94V-0 marking and date code required.

The following files have been bundled within the ZIP file for quotation and manufacture of the PCB.

FILE NAME	DESCRIPTION	FILE FORMAT
TOP.ART	TOP COPPER LAYER	GERBER
SILKTOP.ART	TOP SILKSCREEN	GERBER
SOLDERMASKTOP.ART	TOP SOLDERMASK	GERBER
PASTEMASKTOP.ART	TOP PASTE MASK	GERBER
BOTTOM.ART	BOTTOM COPPER LAYER	GERBER
SILKBOTTOM.ART	BOTTOM SILKSCREEN	GERBER
SOLDERMASKBOTTOM.ART	BOTTOM SOLDERMASK	GERBER
PASTEMASKTBOTTOM.ART	BOTTOM PASTE MASK	GERBER
FABRICATION.ART	FABRICATION/MECHNICAL LAYER	GERBER
NCDRILL-1-2.DRL	NC DRILL FILE	EXCELLON, ASCII
NETLIST.IPC	NETLIST FILE	IPC-D-356A
GSEVBHB08T-BRDSPEC.PDF	PCB SPEC FILE (THIS FILE)	PDF
GSEVBHB08T-B_FAB.PDF	FABRICATION DRAWING	PDF
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